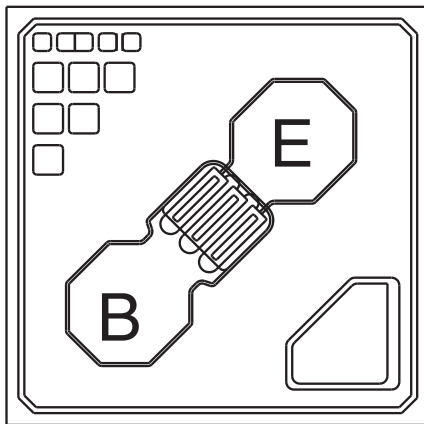


**PROCESS DETAILS**

Process	EPITAXIAL PLANAR
Die Size	16 x 16 MILS
Die Thickness	8.0 MILS
Base Bonding Pad Area	3.75 x 3.75 MILS
Emitter Bonding Pad Area	3.75 x 3.75 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Au - 10,000Å

**GEOMETRY**



BACKSIDE COLLECTOR R0

**GROSS DIE PER 4 INCH WAFER**

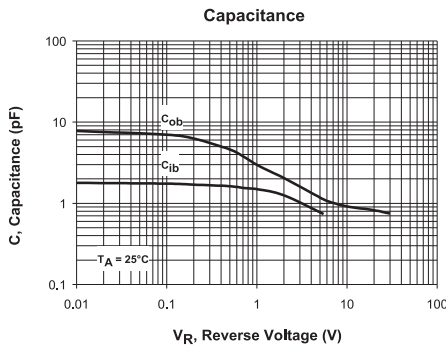
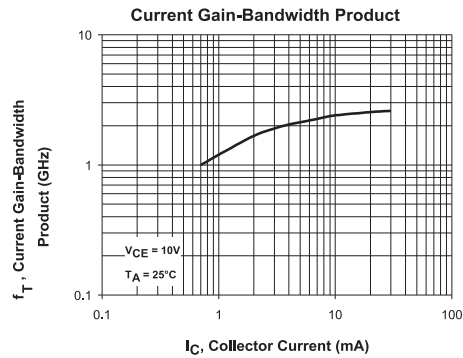
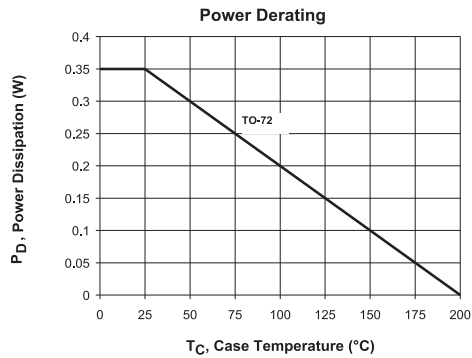
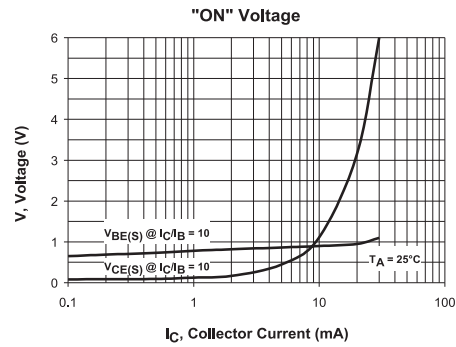
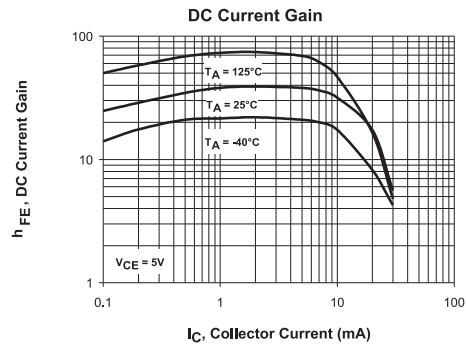
44,140

**PRINCIPAL DEVICE TYPES**

CM4957

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R2 (1-August 2002)



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